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PACKAGING INFORMATION

5962-8409301VFA.A 5962-8409301VFA.A 5962-8409301VFA.A 84093012A 8409301EA SN54HC153J SN54HC153J.A SN74HC153D SN74HC153DR	Active Active Active Active	Production Production Production Production Production	CDIP (J) 16 CDIP (J) 16 CFP (W) 16 CFP (W) 16 LCCC (FK) 20	25 TUBE 25 TUBE 25 TUBE 25 TUBE 55 TUBE	No No No	SNPB SNPB SNPB SNPB	N/A for Pkg Type N/A for Pkg Type N/A for Pkg Type N/A for Pkg Type N/A for Pkg Type	-55 to 125 -55 to 125 -55 to 125 -55 to 125	5962-8409301VE A SNV54HC153J 5962-8409301VE A SNV54HC153J 5962-8409301VF A SNV54HC153W 5962-8409301VF A SNV54HC153W 84093012A SNJ54HC
5962-8409301VFA.A 5962-8409301VFA.A 84093012A 8409301EA SN54HC153J SN54HC153J.A SN74HC153D SN74HC153DR	Active Active	Production Production Production	CFP (W) 16	25 TUBE 25 TUBE	No No	SNPB SNPB	N/A for Pkg Type N/A for Pkg Type	-55 to 125 -55 to 125	A SNV54HC153J 5962-8409301VF A SNV54HC153W 5962-8409301VF A SNV54HC153W 84093012A SNJ54HC
5962-8409301VFA.A 84093012A 8409301EA SN54HC153J SN54HC153J.A SN74HC153D SN74HC153DR	Active Active	Production Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	A SNV54HC153W 5962-8409301VF A SNV54HC153W 84093012A SNJ54HC
84093012A 8409301EA SN54HC153J SN54HC153J.A SN74HC153D SN74HC153DR	Active	Production	·						A SNV54HC153W 84093012A SNJ54HC
8409301EA SN54HC153J SN54HC153J.A SN74HC153D SN74HC153DR			LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54HC
SN54HC153J SN54HC153J.A SN74HC153D C SN74HC153DR	Active	Production							153FK
SN54HC153J.A SN74HC153D C SN74HC153DR			CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8409301EA SNJ54HC153J
SN74HC153D C SN74HC153DR	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54HC153J
SN74HC153DR	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54HC153J
	Obsolete	Production	SOIC (D) 16	-	=	Call TI	Call TI	-40 to 85	HC153
SN74HC153DR.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	HC153
	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC153
SN74HC153DR1G4	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC153
SN74HC153DR1G4.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC153
SN74HC153N	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HC153N
SN74HC153N.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HC153N
SN74HC153NE4	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HC153N
SN74HC153NSR	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC153
SN74HC153NSR.A	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC153
SN74HC153PW C	Obsolete	Production	TSSOP (PW) 16	-	-	Call TI	Call TI	-40 to 85	HC153
SN74HC153PWR	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	HC153
SN74HC153PWR.A	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC153



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Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	(3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SN74HC153PWRG4	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC153
SNJ54HC153FK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	84093012A SNJ54HC 153FK
SNJ54HC153FK.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	84093012A SNJ54HC 153FK
SNJ54HC153J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8409301EA SNJ54HC153J
SNJ54HC153J.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8409301EA SNJ54HC153J

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54HC153, SN54HC153-SP, SN74HC153:

Catalog : SN74HC153, SN54HC153

• Military : SN54HC153

• Space : SN54HC153-SP

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

• Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application